



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.70	<i>h</i>	3.50	2
A <sub>1</sub>	0.40	0.50	0.60	
A <sub>2</sub>	0.90	<i>h</i>	1.50	
$\frac{D}{E}$	35.00 BASIC			
$\frac{D_1}{E_1}$	33.00 REF			
$\frac{e}{e}$	1.00 BASIC			
$\varnothing b$	0.50	0.60	0.70	
aaa	<i>h</i>	<i>h</i>	0.20	
ccc	<i>h</i>	<i>h</i>	0.35	
ddd	<i>h</i>	<i>h</i>	0.30	
eee	<i>h</i>	<i>h</i>	0.10	
M	34			

FF1156 - Sn/Pb SOLDER BALLS  
FFG1156 - Sn/Ag/Cu SOLDER BALLS

**NOTES:**

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. CONFORMS TO JEDEC MS-034-AAR-1

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/04/09	1.0	Initial Xilinx release.

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